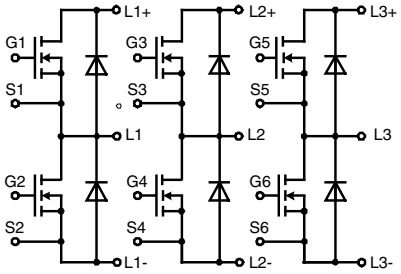
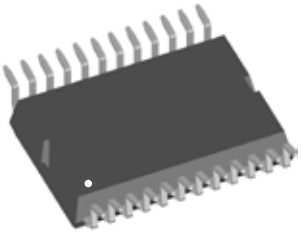
Three phase full Bridge

with Trench MOSFETs
in DCB isolated high current package

V_{DSS} = 75 V
I_{D25} = 110 A
$R_{DSon\ typ.}$ = 4.0 mΩ





MOSFETs

Symbol	Conditions	Maximum Ratings	
V_{DSS}	T_{VJ} = 25°C to 150°C	75	V
V_{GS}		± 20	V
I_{D25}	T_C = 25°C	110	A
I_{D90}	T_C = 90°C	85	A
I_{F25}	T_C = 25°C (diode)	110	A
I_{F90}	T_C = 90°C (diode)	80	A

Symbol	Conditions		Characteristic Values (T_{VJ} = 25°C, unless otherwise specified) min.	typ.	max.	
R_{DSon} [1]	on chip level at V_{GS} = 10 V	T_{VJ} = 25°C		4.0	4.9	mΩ
		T_{VJ} = 125°C		7.2	8.4	mΩ
$V_{GS(th)}$	V_{DS} = 20 V; I_D = 1 mA		2.0		4.0	V
I_{DSS}	V_{DS} = V_{DSS}; V_{GS} = 0 V	T_{VJ} = 25°C			1	µA
		T_{VJ} = 125°C		50		µA
I_{GSS}	V_{GS} = ± 20 V; V_{DS} = 0 V				0.2	µA
Q_g	V_{GS} = 10 V; V_{DS} = 36 V; I_D = 25 A			115		nC
Q_{gs}				30		nC
Q_{gd}				30		nC
$t_{d(on)}$	inductive load V_{GS} = 10 V; V_{DS} = 30 V I_D = 80 A; R_G = 39 Ω; T_J = 125°C			130		ns
t_r				100		ns
$t_{d(off)}$				500		ns
t_f				100		ns
E_{on}				0.20		mJ
E_{off}				0.50		mJ
E_{recoff}				0.01		mJ
R_{thJC}					1.0	K/W
R_{thJH}	with heat transfer paste (IXYS test setup)			1.3	1.6	K/W

[1] $V_{DS} = I_D \cdot (R_{DS(on)} + 2R_{Pin\ to\ Chip})$

Applications

AC drives
- in automobiles
  - electric power steering
  - starter generator
- in industrial vehicles
  - propulsion drives
  - fork lift drives
- in battery supplied equipment

Features

- MOSFETs in trench technology:
  - low R_{DSon}
  - optimized intrinsic reverse diode
- package:
  - high level of integration
  - high current capability
  - aux. terminals for MOSFET control
  - terminals for soldering or welding connections
  - isolated DCB ceramic base plate with optimized heat transfer
- Space and weight savings

Recommended replacement: MTI90WX75GD

Source-Drain Diode

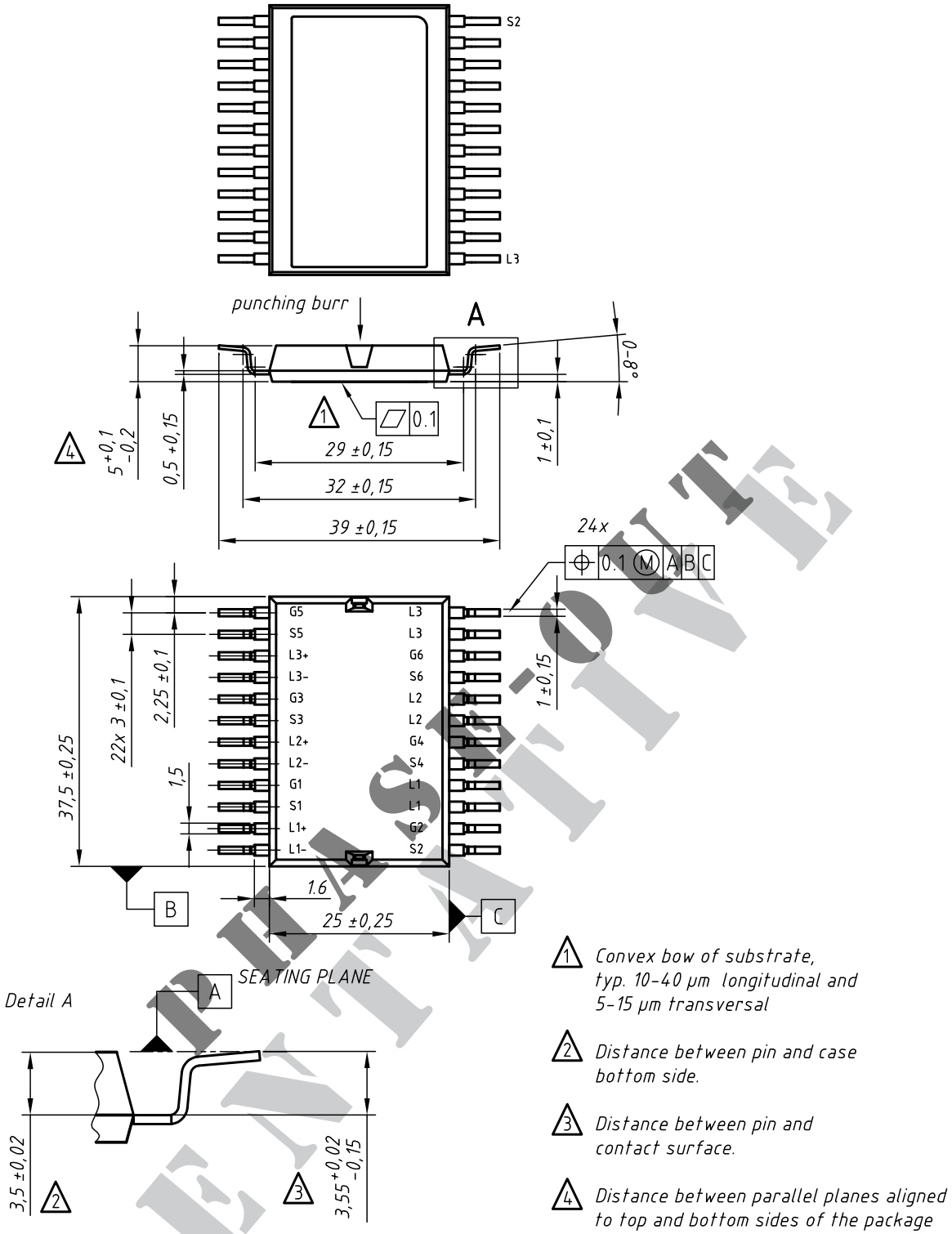
Symbol	Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
V_{SD}	(diode) I_F = 80 A; V_{GS} = 0 V		0.9	1.2	V
t_{rr}	I_F = 80 A; -di_F/dt = 800 A/µs; V_R = 30 V		55		ns
Q_{RM}			0.9		µC
I_{RM}			30		A

Component

Symbol	Conditions	Maximum Ratings	
I_{RMS}	per pin in main current paths (P+, N-, L1, L2, L3) may be additionally limited by external connections 2 pins for output L1, L2, L3	75	A
T_J		-55...+175	°C
T_{stg}		-55...+125	°C
V_{ISOL}	$I_{ISOL} \leq$ 1 mA, 50/60 Hz, f = 1 minute	1000	V~
F_C	mounting force with clip	50 - 250	N

Symbol	Conditions	Characteristic Values min.	typ.	max.	
$R_{pin\ to\ chip}$ [1)]			tbd		mΩ
C_P	coupling capacity between shorted pins and back side metallization		160		pF
Weight			25		g

[1)] $V_{DS} = I_D \cdot (R_{DS(on)} + 2R_{Pin\ to\ Chip})$



1 Convex bow of substrate, typ. 10-40 µm longitudinal and 5-15 µm transversal

2 Distance between pin and case bottom side.

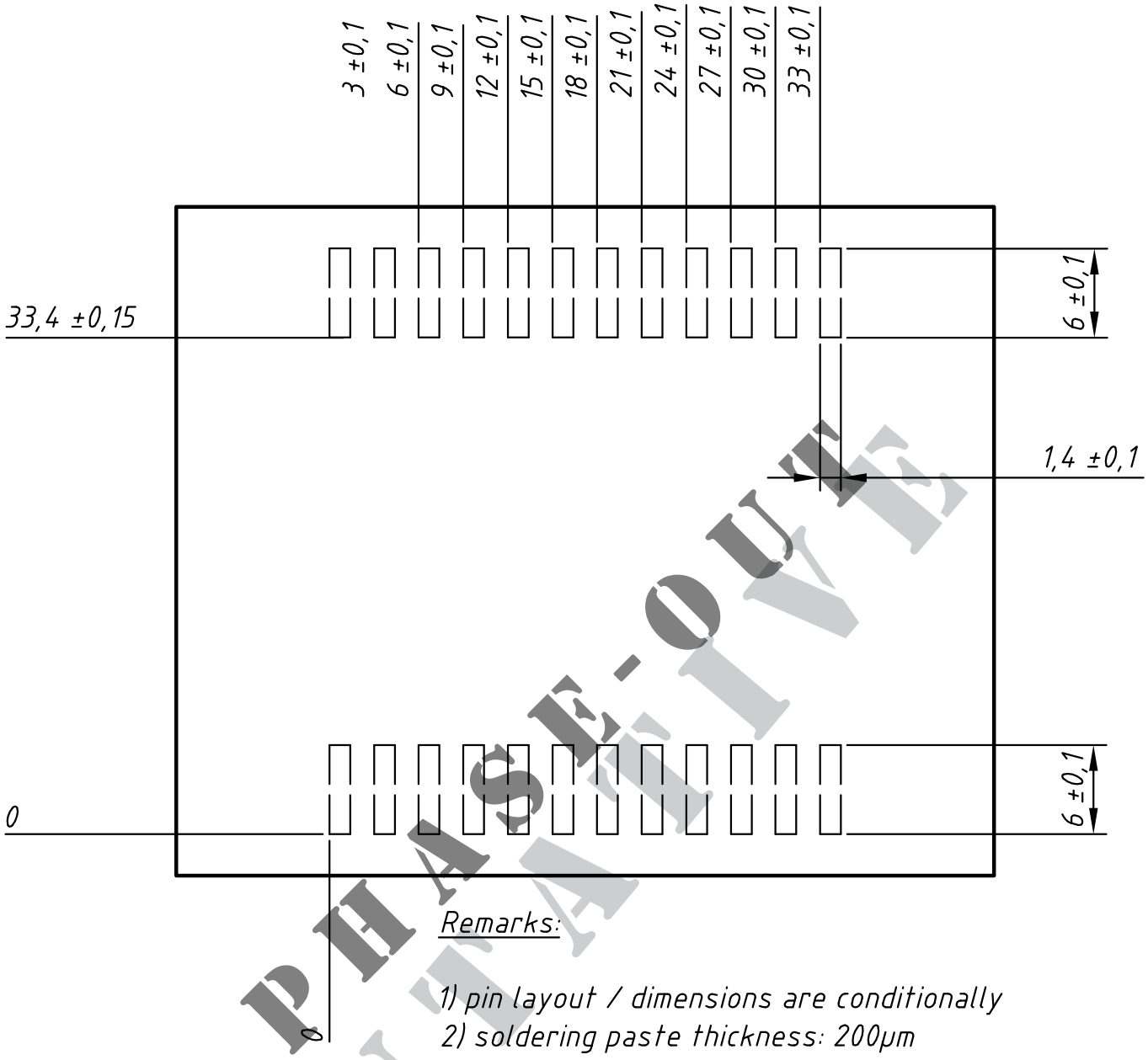
3 Distance between pin and contact surface.

4 Distance between parallel planes aligned to top and bottom sides of the package

contact pin:
- galv. tin plating, per pin side: Sn 10...25 µm, undercoating Ni 0,2...1 µm
- stamping edges may be free of tin
- puching burr: ≤ 0,05mm

Leads	Ordering	Part Name & Packing Unit Marking	Part Marking	Delivering Mode	Base Qty.	Ordering Code
SMD	Standard	GMM 3x120-0075X2 - SMD	GMM 3x120-0075X2	Blister	28	507 508

IXYS reserves the right to change limits, test conditions and dimensions. 20110307



Remarks:

1) pin layout / dimensions are conditionally
2) soldering paste thickness: 200µm